Product-Information

SMT Pins



Features and Benefits

- Individual pins can be randomly placed.
- Pins don't float during reflow.
- Pins are reliably perpendicular.
- Zierick offers pins that are designed for .100° on-center applications.
- Certain pins can be selectively plated.
- Many can be produced in differentlengths or with different materials for higher conductivity.
- Others provide Z-Axis (axial) compliancy and/or can be used in parallel PCB stacking applications.
- All are designed for automationusing the customer's existing pick and place equipment and a special feeder.
- No time-consuming hand placement or costly fixturing is required



Produkt Discription

SMT pins and posts are specially designed for highreliability PCB interconnection applications. They are available in many lengths and diameters.

To reduce the applied cost and increase interconnection reliability, Zierick utilizes the capillary action of reflowing solder to prevent the component from floating and moving on top of the melted solder, and to improve solder joint strength.

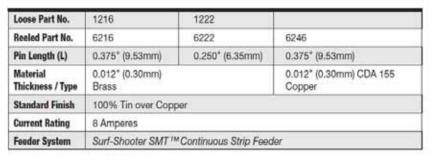
Pull-force tests reveal that a post with proper capillaryaction has much higher retention to the printed circuit board than a post without the capillary action feature. The higher retention force is attributable to two conditions: The first is the very thin layer of solder between the base of the pin and the solder pad. Solder is a weak alloy with a low yield stress. A thicker layer of solder will fail before a thinner layer.

As the solder paste reflows, flux and other active ingredients in the solder cause out-gassing. These gases get trapped under a relatively large surface like the base of the pin. The trapped gasses create voids in the solder that are clearly visible when the pin is pulled off or the solder joint is cross-sectioned. Pins that employ capillary action have fewer and smaller voids because the capillary tube provides a way for gasses to escape.

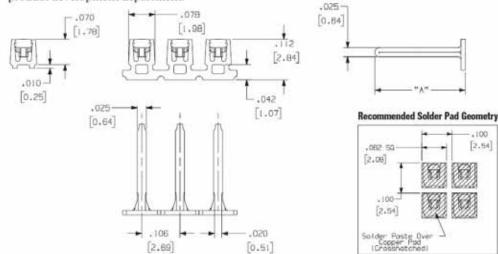
Part Numbers 1216, 6216, 1222, 6222, 6246

U.S. Patent Nos. 5,632,629, 5,695,348, 5,730,608, 5,816,868 and other U.S. and international patents

Zierick recommends .006' stencil thickness for most applications. For other stencil thicknesses, call Zierick's product development department.



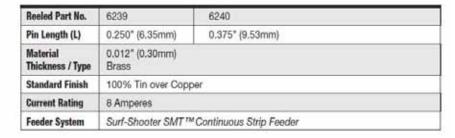
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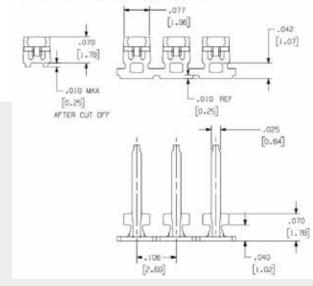


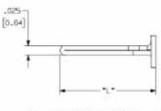
Part Numbers 6239, 6240

U.S. Patent Nos. 5,632,629, 5,695,348, 5,730,608, 5,816,868 and other U.S. and international patents

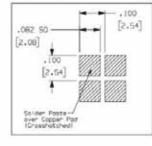
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Recommended Solder Pad Geometry



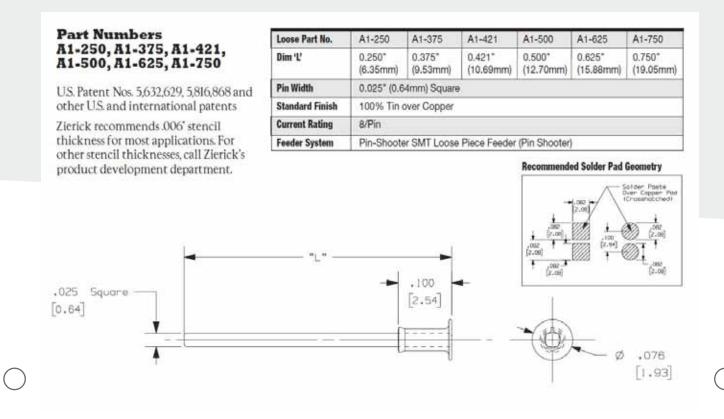


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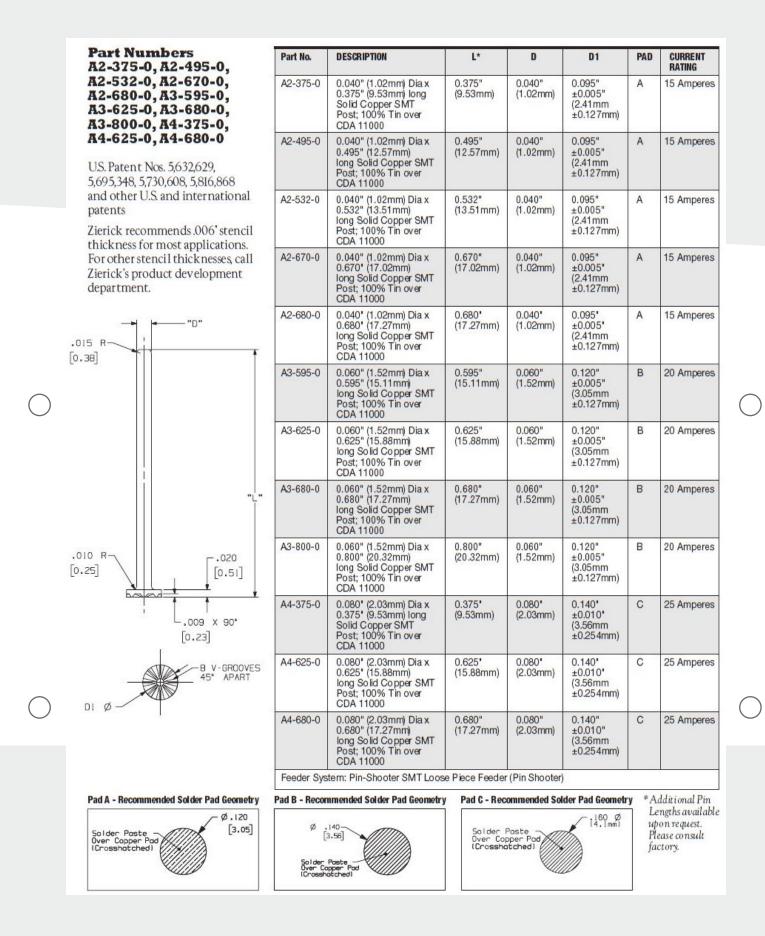
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